

LTM4624-BGA, 25LD 6.25mm X 6.25mm X 5.01mm (TABLE OF MATERIAL DECLARATION)

The LTM4624 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.0451	Barium Compounds	7727-43-7	0.00101	2.24
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2 non-disclosure	0.01553	34.4
				Copper Metal	7440-50-8	0.01332	29.51
				Copper Compounds	147-14-8	0.00001	0.02
				Ecotoxic substances	7440-38-2 7440-28-0	0.00000	0.002002
				Gold metal or alloy	7440-57-5	0.00009	0.21
				Nickel	7440-02-0	0.00071	1.57
				Zinc	7440-66-6	0.00001	0.026
				Continuous Filament Fiber Glass	65997-17-3	0.01220	27.03
				Acrylic Resin	non-disclosure	0.00193	4.27
				Expoxxy Resin	non-disclosure	0.00001	0.019
				Chromium (III) oxide	1308-38-9	0.00000	0.001
				Silica amorphous	7631-86-9	0.00002	0.051
				Talcinot containing fibers like asbestos	14807-96-6	0.00012	0.26
				Arcomatic carbonyl compounds	non-disclosure	0.00011	0.24
				Cyanoguanidine	461-58-5	0.00000	0.007
				Calcium Caobonate	471-34-1	0.00000	0.004
				Amine compounds	non-disclosure	0.00001	0.033
				Leveling agent and others	non-disclosure	0.00004	0.099
2	Solder Paste	Alloy	0.0083	Sn	7440-31-5	0.00784	95.0
				Sb	7440-36-0	0.00041	5.0
3	Passive/Active Components		0.1809	Iron Powder (Fe)	7439-89-6	0.14215	78.55873446
				Copper (Cu)	7440-50-8	0.03475	19.20170904
				Nickel (Ni)	7440-02-0	0.00050	0.278999724
				Tin (Sn)	7440-31-5	0.00119	0.655444874
				Ceramic (Ba) Compounds	12047-27-7	0.00236	1.305111909
4	Active Ics	Silicon	0.0016	Silicon	7440-21-3	0.00161	100
5	Wire	Gold	0.0014	Au	7440-57-5	0.00140	99.99
6	Solder Ball	SAC305	0.0420	Sn	7440-31-5	0.04048	96.5
				Ag	7440-22-4	0.00126	3
				Cu	7440-50-8	0.00021	0.5
7	Encapsulation	Epoxy Resin	0.2457	Fused Silica	60676-86-0	0.18965	77.2
				Epoxy Resin	non-disclosure	0.02186	8.9
				Phenol Resin	non-disclosure	0.02186	8.9
				Crytalline Silica	14808-60-7	0.00737	3.0
				Carbon Black	1333-86-4	0.00123	0.5
				Metal Hydroxide	non-disclosure	0.00368	1.5
Total Package Weight			0.5249				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts